



Material Content Data Sheet



Sales Product Name		BSO130P03S H		Issued		26. September 2017		
MA#		MA000734810						
Package		PG-DSO-8-39		Weight*		83.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.447	2.92	2.92	29186	29186
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		489	
	non noble metal	iron	7439-89-6	0.820	0.98		9777	
wire	non noble metal	copper	7440-50-8	33.276	39.70	40.74	396969	407357
	non noble metal	copper	7440-50-8	0.189	0.23	0.23	2255	2255
	encapsulation	organic material	carbon black	1333-86-4	0.227	0.27		2710
plastics	plastics	epoxy resin	-	7.042	8.40		84009	
	inorganic material	silicondioxide	60676-86-0	38.163	45.52	54.19	455274	541993
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9709	9709
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	866	866
glue	plastics	epoxy resin	-	0.109	0.13		1295	
	noble metal	silver	7440-22-4	0.615	0.73	0.86	7339	8634
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com